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Oohashi et al.

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(54) **ABSORPTION BOARD FOR AN ELECTRIC CHUCK USED IN SEMICONDUCTOR MANUFACTURE**

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(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (8) Cl.** **13-03**

(52) **U.S. Cl.** **D13/182**

(58) **Field of Classification Search** D13/182;
156/345.53; 279/128; 361/234

See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

3,078,565	A *	2/1963	Sanders	29/527.6
4,502,094	A *	2/1985	Lewin et al.	361/234
5,350,479	A *	9/1994	Collins et al.	156/345.53
5,671,116	A *	9/1997	Husain	361/234
6,033,478	A *	3/2000	Kholodenko	118/500
6,278,600	B1 *	8/2001	Shamouilian et al.	361/234
6,628,503	B2 *	9/2003	Sogard	361/324
6,721,162	B2 *	4/2004	Weldon et al.	361/234
2002/0027762	A1 *	3/2002	Yamaguchi	361/234
2002/0159217	A1 *	10/2002	Tsuruta et al.	361/234

2004/0177927	A1	9/2004	Kikuchi et al.	
2004/0179323	A1 *	9/2004	Litman et al. 361/234
2004/0190215	A1 *	9/2004	Weldon et al. 361/234
2004/0212947	A1 *	10/2004	Nguyen et al. 361/234
2004/0218339	A1 *	11/2004	Nakamura 361/234
2005/0111161	A1 *	5/2005	Tran 361/234
2005/0146277	A1	7/2005	Ueda et al.	
2006/0002053	A1 *	1/2006	Brown et al. 361/234
2006/0164785	A1 *	7/2006	Pellegrin 361/234
2006/0221539	A1 *	10/2006	Morita et al. 361/234

FOREIGN PATENT DOCUMENTS

JP	D1041644	6/1999
JP	2004-047653	2/2004
JP	D1197395	2/2004

* cited by examiner

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(57) **CLAIM**

We claim the ornamental design for an absorption board for an electric chuck used in semiconductor manufacture, as shown.

DESCRIPTION

FIG. 1 is a perspective view of an absorption board for an electric chuck used in semiconductor manufacture.

FIG. 2 is a front elevational view thereof.

FIG. 3 is a rear elevational view thereof.

FIG. 4 is a right side elevational view thereof, the left side elevational view being a mirror image and not shown; and,

FIG. 5 is a top plan view thereof, the bottom plan view being a mirror image and not shown.

1 Claim, 4 Drawing Sheets

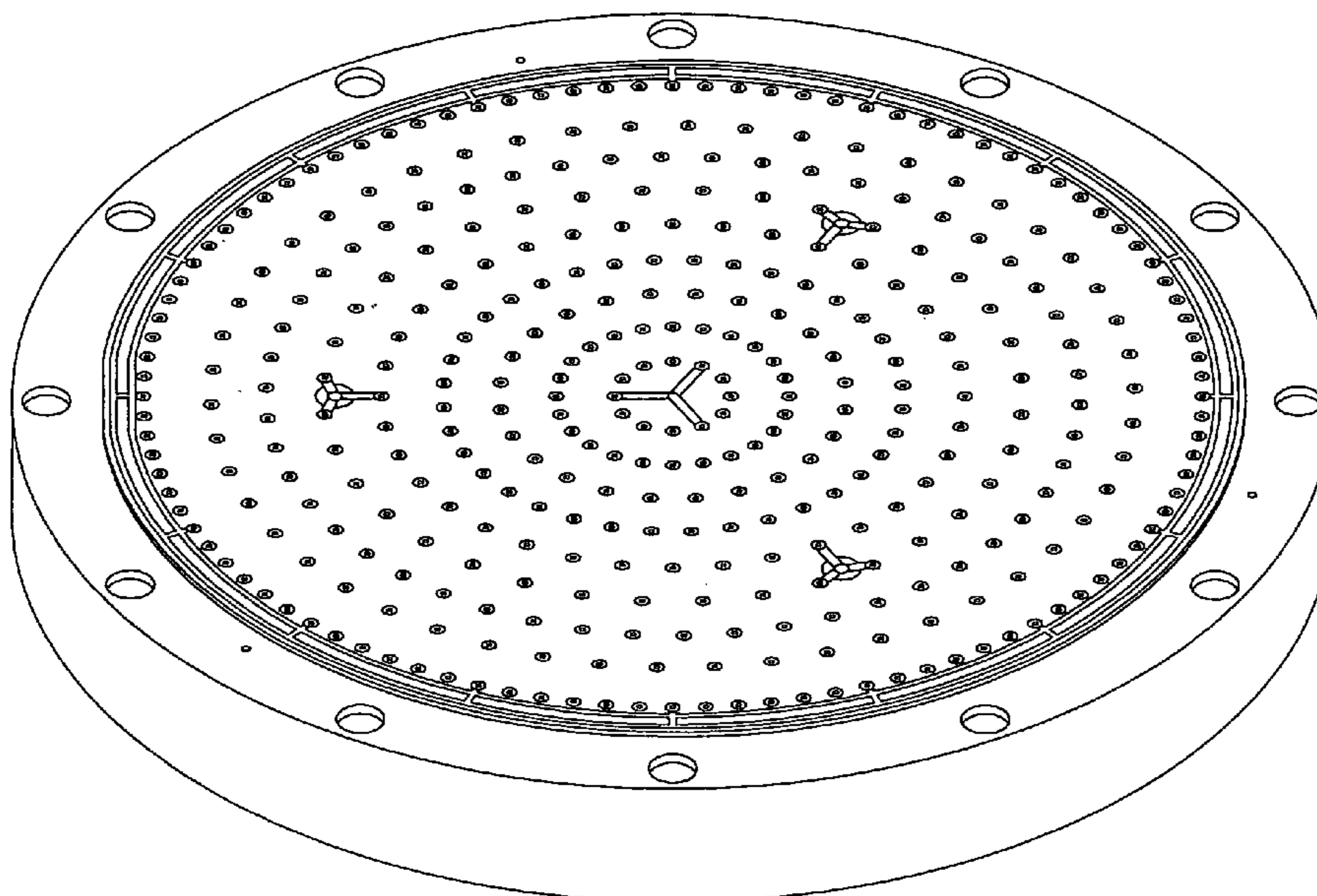


FIG. 1

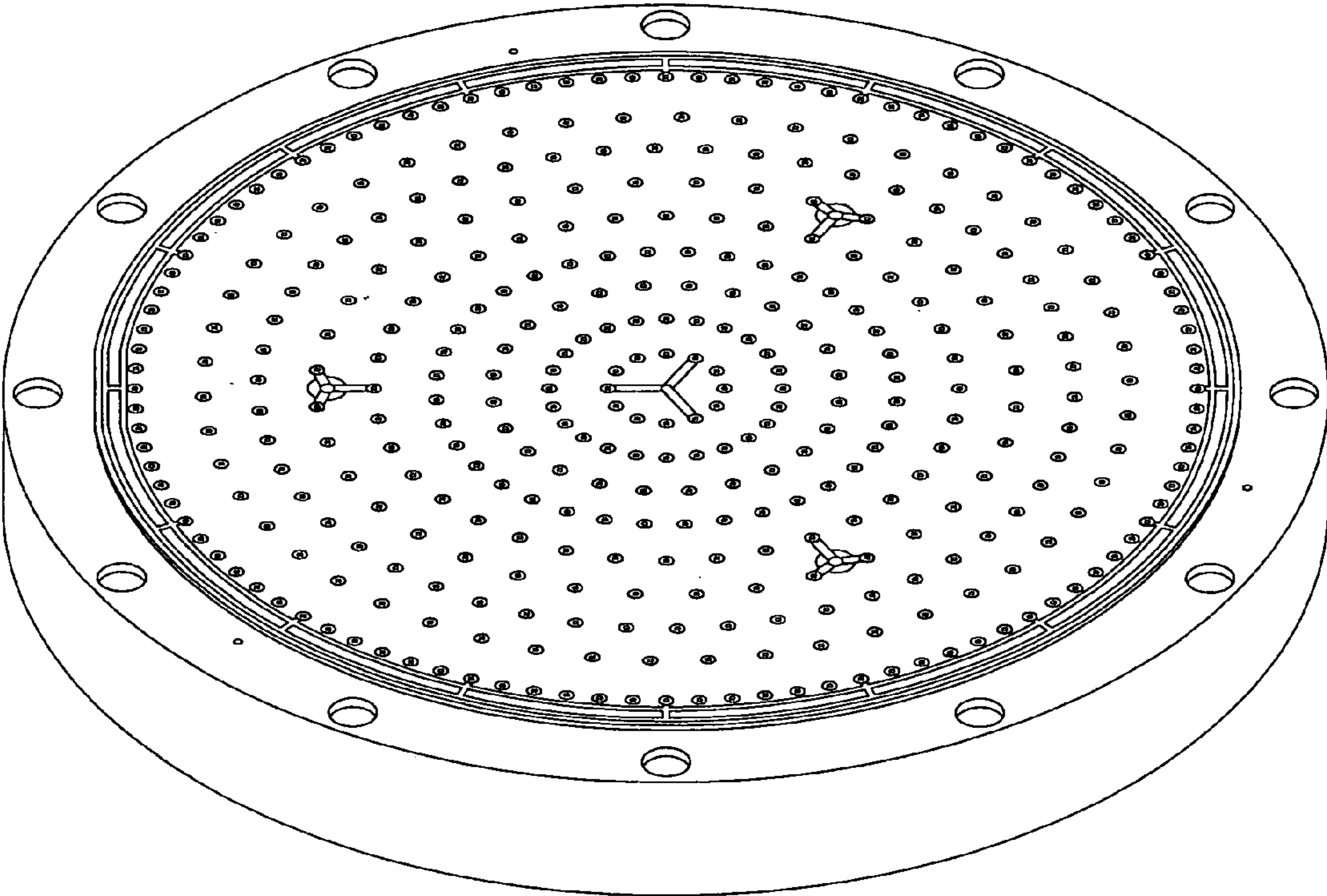


FIG. 2

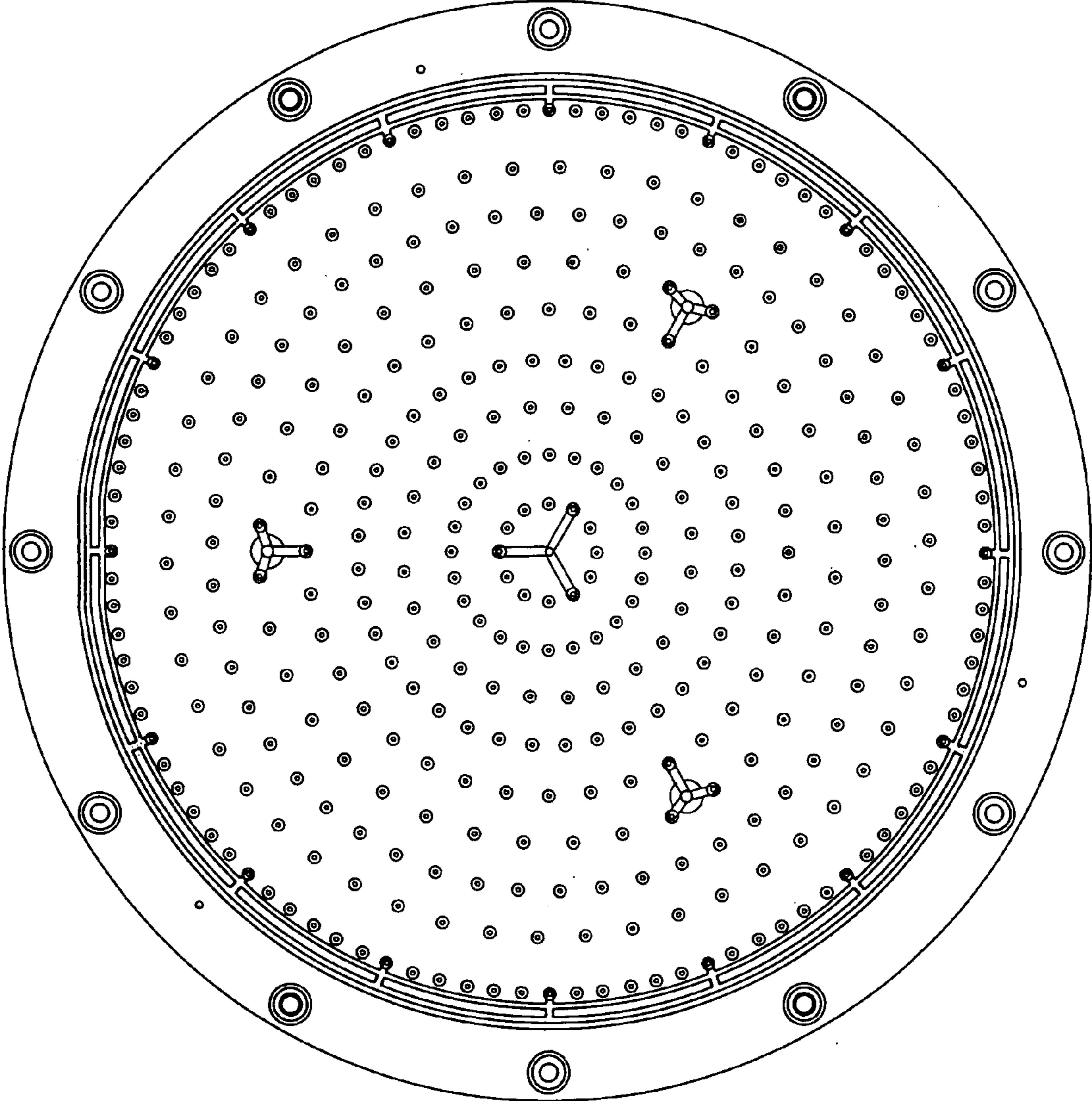


FIG. 3

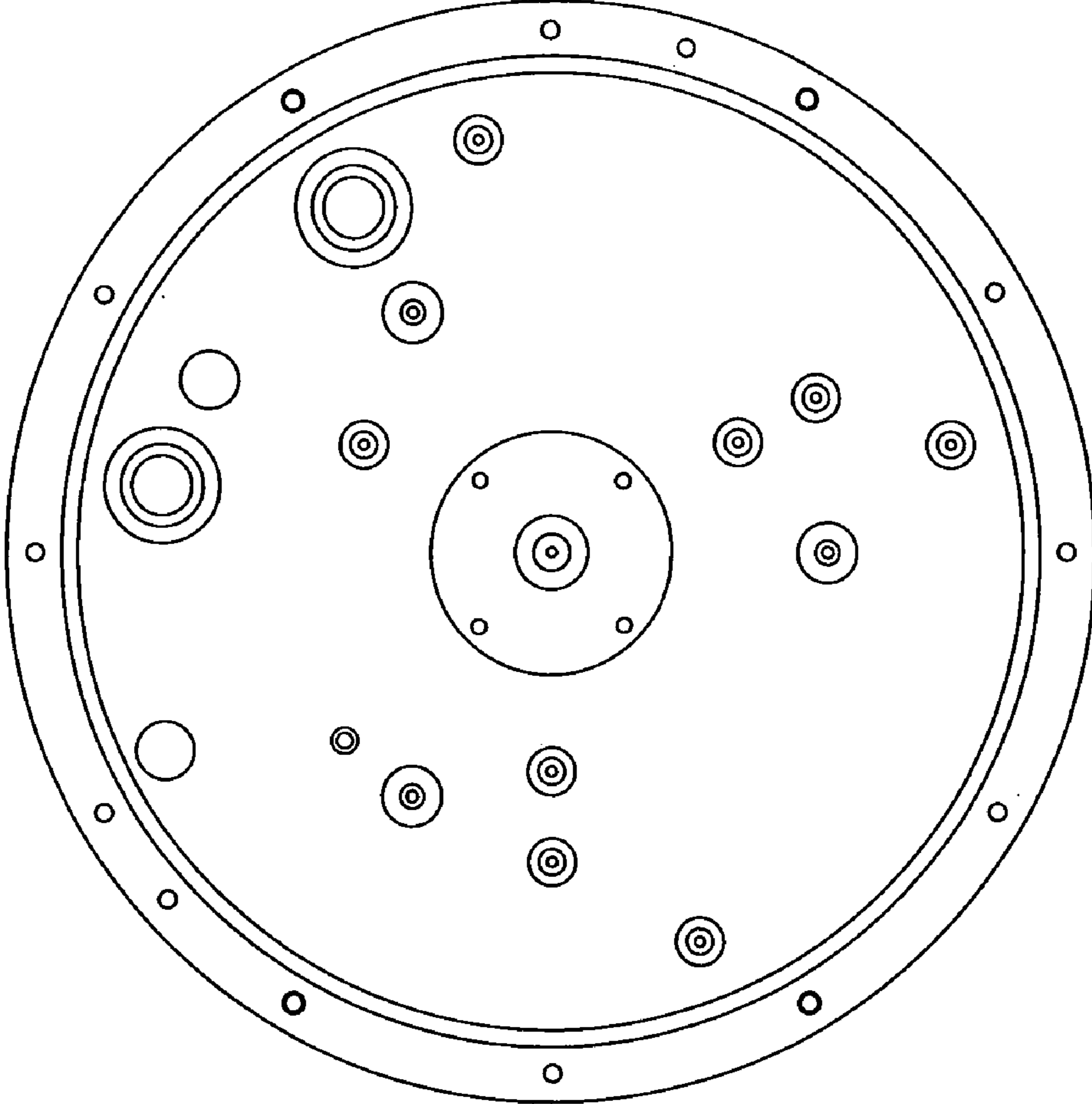


FIG. 4

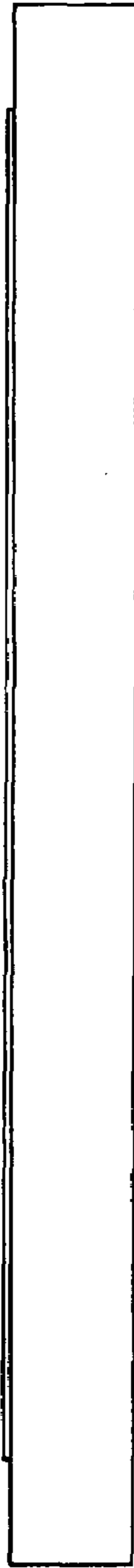


FIG. 5

